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Please note: As part of the Fairchild Semiconductor integration, some of the Fairchild orderable part numbers will need to change in order to meet ON Semiconductor's system requirements. Since the ON Semiconductor product management systems do not have the ability to manage part nomenclature that utilizes an underscore (_), the underscore (_) in the Fairchild part numbers will be changed to a dash (-). This document may contain device numbers with an underscore (_). Please check the ON Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.onsemi.com. Please email any questions regarding the system integration to Fairchild guestions@onsemi.com.

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FQP8N90C / FQPF8N90C N-Channel QFET® MOSFET

900 V, 6.3 A, 1.9 Ω

Description

This N-Channel enhancement mode power MOSFET is • 6.3 A, 900 V, $R_{DS(on)}$ = 1.9 Ω (Max.) @ V_{GS} = 10 V, produced using ON Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state • Low Gate Charge (Typ. 35 nC) resistance, and to provide superior switching performance

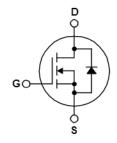
• Low Crss (Typ. 12 pF) and high avalanche energy strength. These devices are suitable for switched mode power supplies, active power • 100% Avalanche Tested factor correction (PFC), and electronic lamp ballasts.

Features

- $I_D = 3.15 A$







Absolute Maximum Ratings T_C = 25°C unless otherwise noted.

Symbol	Parameter		FQP8N90C	FQPF8N90C	Unit
V _{DSS}	Drain-Source Voltage		90	00	V
I _D	Drain Current - Continuous (T _C = 25°C)		6.3	6.3 *	А
	- Continuous (T _C = 100°C)		3.8	3.8 *	Α
I _{DM}	Drain Current - Pulsed	(Note 1)	25	25 *	Α
V _{GSS}	Gate-Source Voltage		± 30		V
E _{AS}	Single Pulsed Avalanche Energy (Note 2)		850		mJ
I _{AR}	Avalanche Current (Note		6.3		А
E _{AR}	Repetitive Avalanche Energy (N		17.1		mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	4.0		V/ns
P_{D}	Power Dissipation (T _C = 25°C)		171	60	W
	- Derate above 25°C		1.37	0.48	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150		°C
T _L	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 Seconds		30	00	°C

^{*} Drain current limited by maximum junction temperature.

Thermal Characteristics

Symbol	Parameter	FQP8N90C	FQPF8N90C	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Max.	0.73	2.08	°C/W
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink Typ, Max.	0.5		°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient, Max.	62.5	62.5	°C/W

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FQP8N90C	FQP8N90C	TO-220	Tube	N/A	N/A	50 units
FQPF8N90C	FQPF8N90C	TO-220F	Tube	N/A	N/A	50 units

Electrical Characteristics

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Cha	racteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	900			V
ΔBV_{DSS} / ΔT_{J}	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced to 25°C		0.95		V/°C
I _{DSS}	Zoro Coto Voltogo Droin Current	V _{DS} = 900 V, V _{GS} = 0 V			10	μΑ
	Zero Gate Voltage Drain Current	V _{DS} = 720 V, T _C = 125°C			100	μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30 V, V _{DS} = 0 V			100	nΑ
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -30 V, V _{DS} = 0 V			-100	nΑ

On Characteristics

V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$	3.0		5.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 3.15 A		1.6	1.9	Ω
g _{FS}	Forward Transconductance	V _{DS} = 50 V, I _D = 3.15 A		5.5		S

Dynamic Characteristics

C _{iss}	Input Capacitance	V _{DS} = 25 V, V _{GS} = 0 V,	 1600	2080	pF
Coss	Output Capacitance	f = 1.0 MHz	 130	170	pF
C _{rss}	Reverse Transfer Capacitance		 12	15	pF

Switching Characteristics

t _{d(on)}	Turn-On Delay Time	V _{DD} = 450 V, I _D = 8 A,	 40	90	ns
t _r	Turn-On Rise Time	$R_G = 25 \Omega$	 110	230	ns
t _{d(off)}	Turn-Off Delay Time		 70	150	ns
t _f	Turn-Off Fall Time	(Note 4)	 70	150	ns
Q_g	Total Gate Charge	V _{DS} = 720 V, I _D = 8 A,	 35	45	nC
Q_{gs}	Gate-Source Charge	V _{GS} = 10 V	 10		nC
Q_{gd}	Gate-Drain Charge	(Note 4)	 14		nC

Drain-Source Diode Characteristics and Maximum Ratings

Is	Maximum Continuous Drain-Source Diode Forward Current		 	6.3	А
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current		 	25	Α
V _{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 6.3 \text{ A}$	 	1.4	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _S = 8 A,	 530		ns
Q _{rr}	Reverse Recovery Charge	dl _F / dt = 100 A/μs	 5.8		μС

- **Notes:**1. Repetitive rating : pulse-width limited by maximum junction temperature.
 2. L = 40 mH, I_{AS} = 6.3 A, V_{DD} = 50 V, R_{G} = 25 Ω , starting T_{J} = 25°C.
 3. I_{SD} \leq 8 A, di/dt \leq 200 A/ μ s , V_{DD} \leq BV $_{DSS}$, starting T_{J} = 25°C.
 4. Essentially independent of operating temperature.

Typical Characteristics

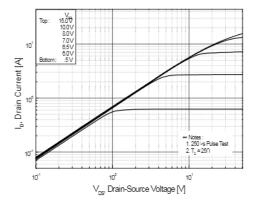


Figure 1. On-Region Characteristics

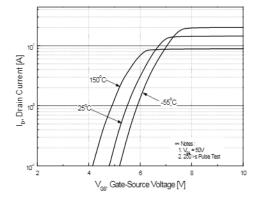


Figure 2. Transfer Characteristics

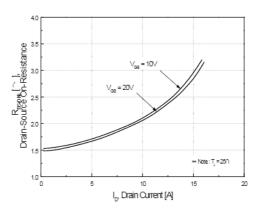


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

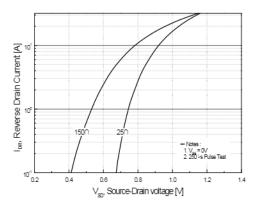


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

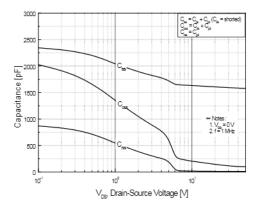


Figure 5. Capacitance Characteristics

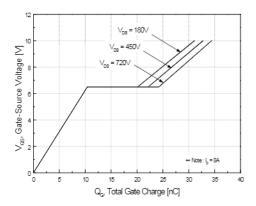


Figure 6. Gate Charge Characteristics

Typical Characteristics (Continued)

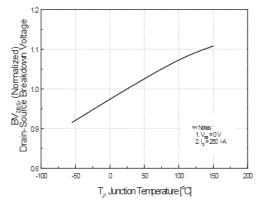


Figure 7. Breakdown Voltage Variation vs Temperature

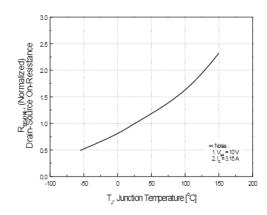


Figure 8. On-Resistance Variation vs Temperature

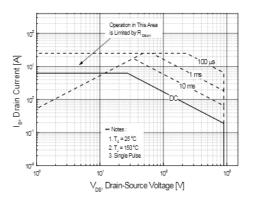


Figure 9-1. Maximum Safe Operating Area for FQP8N90C

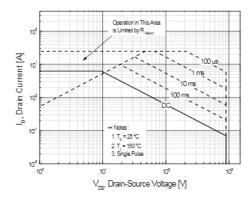


Figure 9-2. Maximum Safe Operating Area for FQPF8N90C

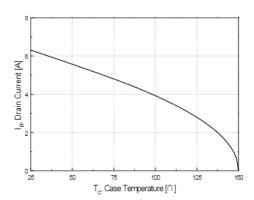


Figure 10. Maximum Drain Current vs Case Temperature

Typical Characteristics (Continued)

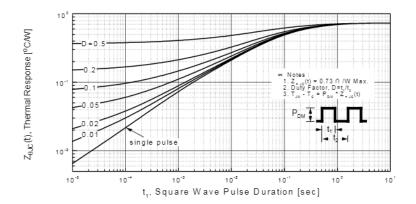


Figure 11-1. Transient Thermal Response Curve for FQP8N90C

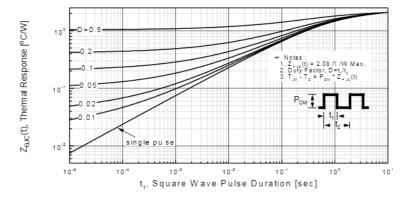


Figure 11-2. Transient Thermal Response Curve for FQPF8N90C

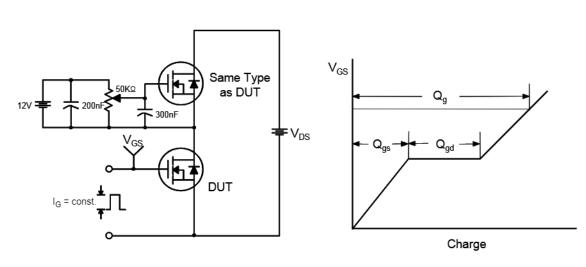


Figure 12. Gate Charge Test Circuit & Waveform

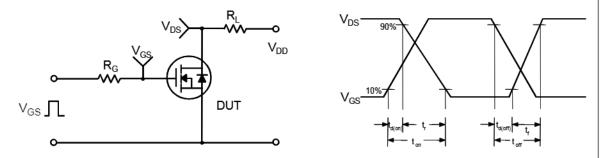


Figure 13. Resistive Switching Test Circuit & Waveforms

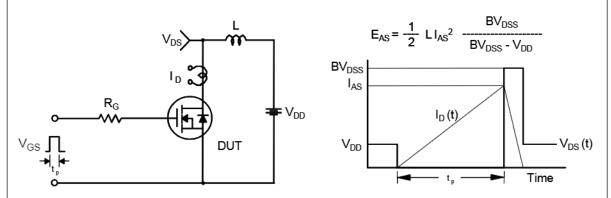
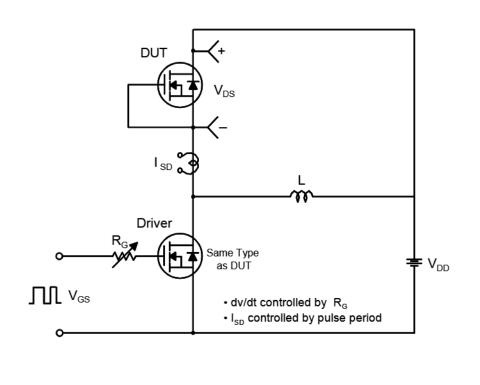


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms



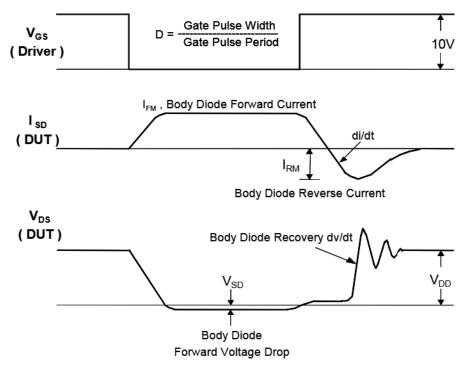
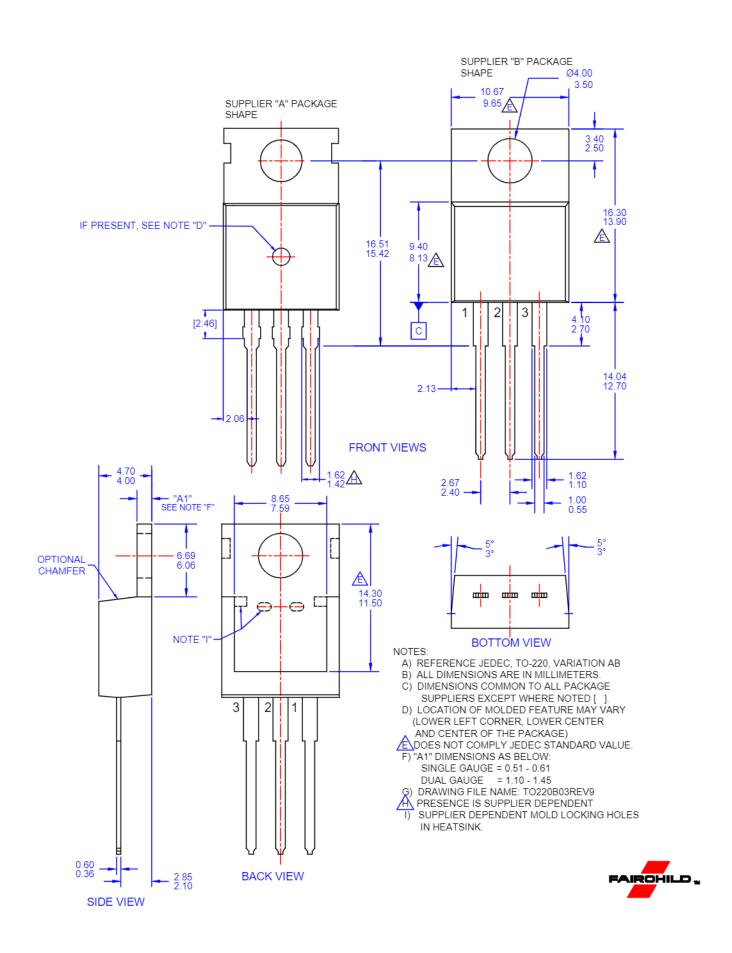
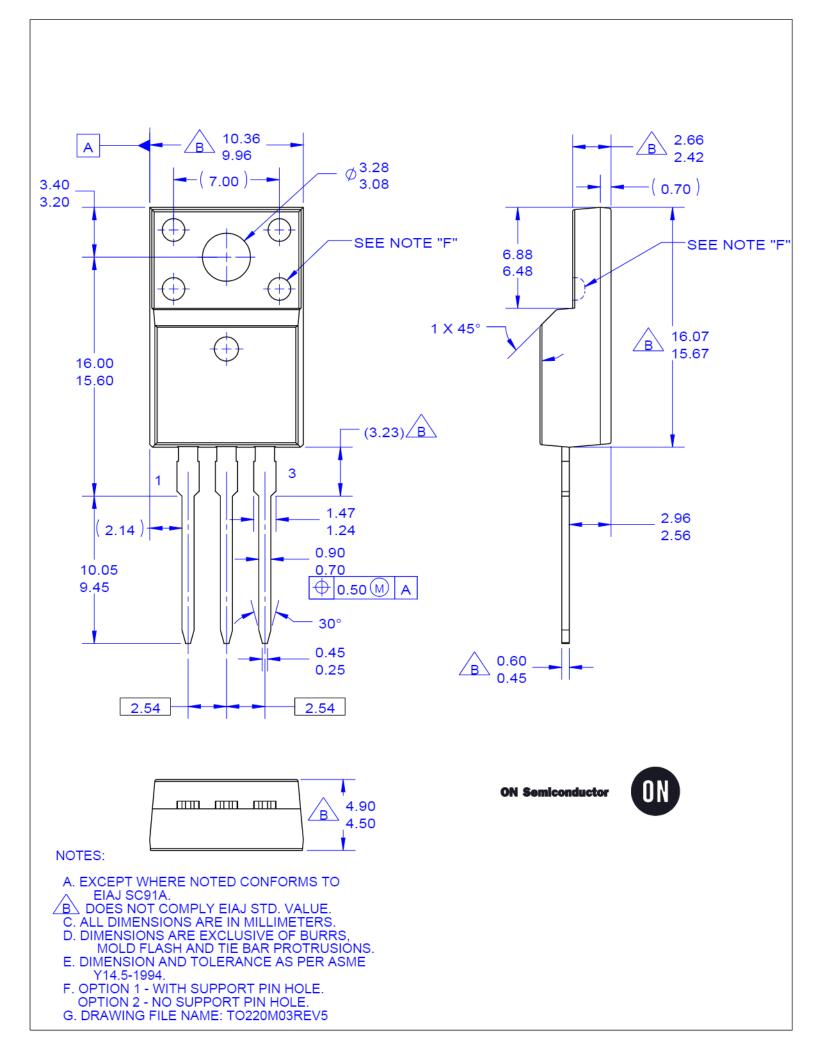


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms





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